

An IATF 16949, ISO9001 and ISO 14001 Certified Company





4A TRIACs

BT136 600/800



TO-220 Leaded Plastic Package RoHS compliant

TO-220

GENERAL DESCRIPTION:

With low holding and latching current,BT136 series triacs are especially recommended for use on middle and small resistance type power load. From all three terminals to external heatsink, BT136 provides a rated insulation voltage of $2500 \, V_{RMS}$, complying with UL standards.

FEATURES:

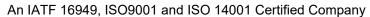
Symbol	Value	Unit
I _{T(RMS)}	4	Α
V_{DRM}/V_{RRM}	600/800	V

APPLICATIONS: High commutation performances applications.

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT	
Storage junction temperature range			-40-150	°C
Operating junction temperature range		T _j	-40-125	°C
Repetitive peak off-state voltage(T _j =25°C)		V_{DRM}	600/800	V
Repetitive peak reverse voltage(T _j =25°C)		V_{RRM}	600/800	V
Non repetitive surge peak Off-state voltage		V_{DSM}	V _{DRM} + 100	V
Non repetitive peak reverse voltage			V _{RRM} + 100	V
RMS on-state current	I _{T(RMS)}	4.0	Α	
Non repetitive surge peak on-state current (full cy	I _{TSM}	35	Α	
I ² t value for fusing (tp=10ms)	l ² t	6.1	A^2s	
Critical rate of rise of an atota current (1 = 2×1)	41/44	50	Λ/110	
Critical rate of rise of on-state current (I _G =2×I _{GT})	IV	dl/dt	10	A/µs
Peak gate current	I _{GM}	2	Α	
Average gate power dissipation	$P_{G(AV)}$	0.5	W	
Peak gate power			5	W









ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)

PARAMETER SYMBOL TEST CONDITION		QUAD-		VALUE			UNIT		
PARAMETER	STWIDUL	TEST CONDITION	RANT		T	D	Е	F	UNII
Gate Trigger Current			I-II-III	MAX	5	5	10	25	mA
Gate Higger Current	I _{GT}	V _D =12V	IV	IVIAA	5	10	25	70	ША
Gate Trigger Voltage	V_{GT}	ם	ALL	MAX	1.3			V	
Non-triggering gate voltage	$V_{\sf GD}$	$V_D = V_{DRM} T_j = 125$ °C R _L =3.3K Ω	ALL	MIN		0	.2		V
Latching current		I _G =1.2IG _⊤	I-III	MAX	10	20	30	40	mA
Latering current	IL	1 _G -1.21 G _T	II-IV	IVIAA	15	35	45	60	шА
Holding current	I _H	I _T =100mA		MAX	5	15	25	30	mA
Critical rate of rise of off-	dV/dt	V _D =2/3V _{DRM} Gate Open T _i =125°C		MIN	20	50	100	150	V/µs
state voltage	aviat	V _D 2/0 V _{DRM} Cate Opoli 1 _j 120 C Will 20 00 100		.00	ν/μο				
Critical rate of decrease									
of commutating on-state	(dV/dt)c	(dl/dt)c=1.7A/ms T _j =12	25°C	MIN	0.1	0.1	0.5	5	V/µs
current		<u> </u>							

STATIC CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	VALUE (Max)	UNIT	
Peak on-state voltage drop	V _{TM}	I _{τM} =5.5A t _p =380μs	T _j =25°C	1.6	V
Maximum forward leakage current	I _{DRM}	$V_D = V_{DRM} V_R = V_{RRM}$	T _j =25°C	10	μA
Maximum Reverse leakage current	I _{RRM}	D DUM V VVIM	T _j =125°C	0.5	mA

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to case thermal resistance	$R_{th(j-c)}$	2.5	°C/W



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TYPICAL CHARACTERISTICS CURVES

Fig 1: Maximum power dissipation versus RMS on-state current

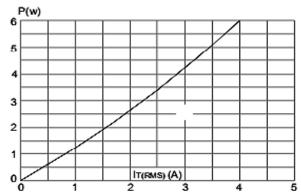


Fig 2: RMS on-state current versus case temperature

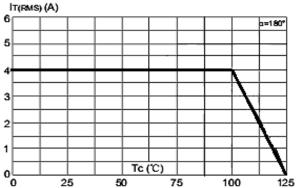


Fig 3: Surge peak on-state current versus number of cycles

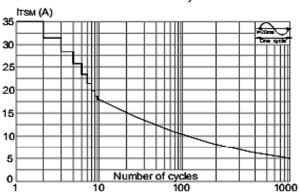


Fig 4: On-state characteristics (maximum values)

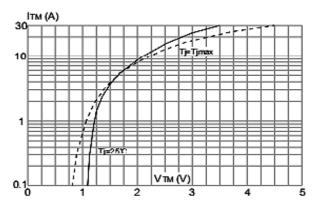


Fig 5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms and corresponding value of I t (I-II-III:dl/dt < 50A/µs; IV:dl/dt < 10A/µs)

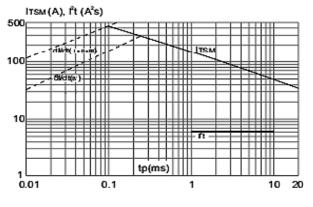
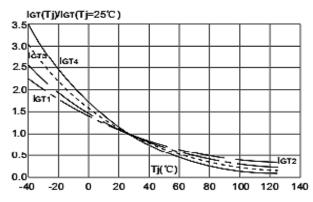
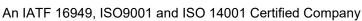


Fig 6: Relative variations of gate trigger current versus junction temperature











TYPICAL CHARACTERISTICS CURVES

Fig 7: Relative variations of holding current versus junction temperature

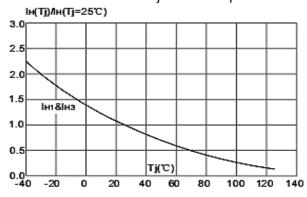
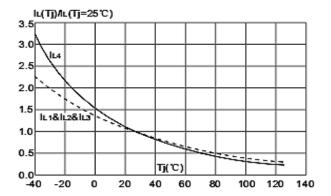
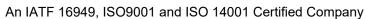


Fig 8: Relative variations of latching current versus junction temperature





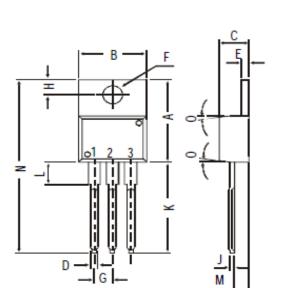






PACKAGE DETAILS

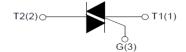
TO-220 Leaded Plastic Package



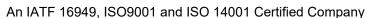
	DIM	MIN.	MAX.	
	Α	14.42	16.51	
	В	9.63	10.67	
	С	3.56	4.83	
	D		0.90	
	E	1.15	1.40	
	F	3.75	3.88	
	G	2.29	2.79	
	Н	2.54	3.43	
i	J		0.56	
	K	12.70	14.73	
2	L	2.80	4.07	
	М	2.03	2.92	
	N		31.24	
Ē	0	DEG 7		

Pin Configuration

- 1. T1
- 2,4. T2
- 3. Gate











Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- $\cdot\,$ The product shall be stored on a plane area. They should not be turned upside down.

They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level					
Level	Time	Condition			
1	Unlimited	≤30 °C / 85% RH			
2	1 Year	≤30 °C / 60% RH			
2a	4 Weeks	≤30 °C / 60% RH			
3	168 Hours	≤30 °C / 60% RH			
4	72 Hours	≤30 °C / 60% RH			
5	48 Hours	≤30 °C / 60% RH			
5a	24 Hours	≤30 °C / 60% RH			
6	Time on Label(TOL)	≤30 °C / 60% RH			



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Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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